

L36: (1) ("6072233").PN
 L37: (1) ("6160705").PN
 L38: (1) ("6172419").PN
 L39: (1) ("6180881").PN
 L40: (1) ("6235554").PN
 L41: (1) ("6258632").PN
 L42: (1) ("6313522").PN
 L43: (1) ("6329709").PN
 L44: (1) ("6369454").PN
 L45: (1) ("6395578").PN
 L46: (1) ("6404046").PN
 L47: (1) ("6448506").PN
 L48: (1) ("6459148").PN
 L49: (1) ("6486537").PN
 L50: (1) ("6501184").PN
 L51: (1) ("6515356").PN
 L52: (1) ("6518659").PN
 L53: (1) ("6577013").PN
 L54: (65039) packag\$3 and ((die chip with (side near substrate)))
 L55: (64497) packag\$3 and ((die chip near (side near substrate)))
 L56: (11) 55 and peripheral near side near substrate
 L57: (0) peripheral near side near substrate near (die chip)
 L58: (241) (peripheral side) near substrate near (die chip)
 L59: (143) substrate near adjacent near (die chip)
 L60: (0) substrate near peripheral near side near (die chip)
 L61: (6) substrate near peripheral near (die chip)
 L62: (157) packag\$3 and ((substrate near (peripheral side peripheral near side)) near (die chip))

- Failed

 (0) 1 and (semiconductor and (die chip))

Search:

DBs: Plastics

Default: Highlight all hit terms initially

packag\$3 and (substrate near (peripheral side peripheral near side)) near (die chip)

U	I	Document ID	Issue Date	Pages	Title	Current CR	Current XRef
1	<input type="checkbox"/>	US 20040197954 A1	20041007	15	Chip scale image sensor semiconductor package and method of fabrication	438/108	
2	<input type="checkbox"/>	US 20040188829 A1	20040930	12	Package with integrated wick layer and method for heat removal	257/712	438/106
3	<input type="checkbox"/>	US 20040178499 A1	20040916	9	Semiconductor package with multiple sides having package contacts	257/734	
4	<input type="checkbox"/>	US 20040164386 A1	20040826	6	Unmolded package for a semiconductor device	257/678	
5	<input type="checkbox"/>	US 20040155337 A1	20040812	19	High density chip level package for the packaging of integrated circuits and	257/738	
6	<input type="checkbox"/>	US 20040150100 A1	20040805	14	Packaging of integrated circuits with carbon nano-tube arrays to enhance heat	257/720	
7	<input type="checkbox"/>	US 20040125580 A1	20040701	10	Mounting capacitors under ball grid array	361/794	361/760
8	<input type="checkbox"/>	US 20040113250 A1	20040617	17	Integrated circuit assembly	257/680	257/723
9	<input type="checkbox"/>	US 20040070080 A1	20040415	15	Low cost, high performance flip chip package structure	257/778	257/E21.503, 257/E23.069
10	<input type="checkbox"/>	US 20040043539 A1	20040304	8	Plastic ball grid array with integral heatsink	438/122	257/E23.092, 438/126
11	<input type="checkbox"/>	US 20040041271 A1	20040304	13	Methods for wafer-level packaging of microelectronic devices and microelectronic	257/759	257/723, 257/738